Tri-state Elastic Buffer Design

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Abstract

For the recent CMOS feature sizes power dissipation becomes an overriding concerns for VLSI circuit design. We propose a novel approach named tri-state elastic buffer design which reduces the total power, area & delay of elastic buffer. The paper presents a design and implementation of tri-state buffer mechanism in 120 nm technology. This design offers also the advantage of third state (High Impedance state) of tri-state buffer. The proposed elastic buffer design using tri-state buffer is implemented in DSCH & MICROWIND tools. The obtained result shows that our design is effective in terms 48.68 % reduction in total power, 5.62 % reduction in delay & 40.98 % reduction in area.

Keywords- Cadence; DSCH; MICROWIND; Total power; delay; Buffer design;

I. INTRODUCTION

Networks-on-chip (NoCs) have been developed to address the communication requirements of large-scale systems enabled by semiconductor technology scaling .Past work has attributed approximately up to 40% of the power and 11% of the area of the overall chip to the NoC.

Elastic buffer using D flip-flop using master and slave latches. By adding control logic to drive the latch enable pins independently, each latch can be used as an independent storage location. Thus, the Flip-flop becomes an Elastic Buffer, a First-In-First-Out with two storage locations. This is illustrated in Figure. Elastic Buffer channels use many such EBs to form a distributed FIFO [1]. FIFO storage can be increased by adding latches to EBs or by using repeater cells for storage [15]. EBs uses a ready-valid handshake to advance a flit (flow-control digit). An upstream *ready* (R) signal indicates that the downstream EB has at least one empty storage location and can store an additional flit. A downstream *valid* (V) signal indicates that the flit currently being driven is valid. A flit advances when both the ready and valid signals between two EBs are asserted at the rising clock edge. This timing convention requires at least two storage slots per clock cycle delay to avoid creating unnecessary pipeline bubbles.

Elastic buffer using D flip-flop in which D flip-flop uses 18 transistors hence master-slave need

36 transistors. The D flip-flop captures the value of the D-input at a definite portion of the clock cycle (such as the rising edge of the clock). That captured value becomes the Q output. At other times, the output Q does not change.

Elastic buffer design using Tri-state buffer have a same working as elastic buffer design using D flip-flop accept one. Elastic buffer design using tri-state buffer offers a third state or high impedance state which a common way for many devices to communicate with one another is on a bus, and that a bus should only have one device writing to it, although it can have many devices reading from it. Since many devices always produce output (such as registers) and these devices are hooked to a bus, we need a way to control what gets on the bus, and what doesn't. A tri state buffer is good for that.

Tri-state buffer can be made using only 6 transistors and hence master-slave needs 12 transistors.

The whole concept of the third state (Hi-Z) is to effectively remove the device's influence from the rest of the circuit. If more than one device is electrically connected, putting an output into the Hi-Z[5] state is often used to prevent short circuits, or one device driving high (logical 1) against another device driving low (logical 0).

The rest of this paper is organized as follows: Section 2
discusses the previous work with the basic building blocks of D flip-flop, circuit diagram of D flip-flop using 18 transistors, truth table , tri-state buffer, circuit diagram of tri-state buffer using 6 transistors, truth table as well as Elastic buffer using D flip-flop .Section 3 proposed Elastic buffer design using Tri-state buffer Section 4 presents the comparison and results with tables. Finally, sections 6 presents conclusion and discuss related work. Later some results obtained from the Cadence is attached with this paper.

II. PREVIOUS WORK
A. DFF Buffer

The D flip-flop is widely used. It is also known as a *data* or *delay* flip-flop. The D flip-flop captures the value of the D-input at a definite portion of the clock cycle (such as the rising edge of the clock). That captured value becomes the Q output. At other times, the output Q does not change. It uses 18 MOS transistor as shown in Figure….due to using

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more number of transistor DFF consumes more power, static and dynamic both and also increase the propagation delay.

Since this buffer uses less transistor hence it consumes less power, static and dynamic both and also have reduced the propagation delay as compared to buffer using DFF.
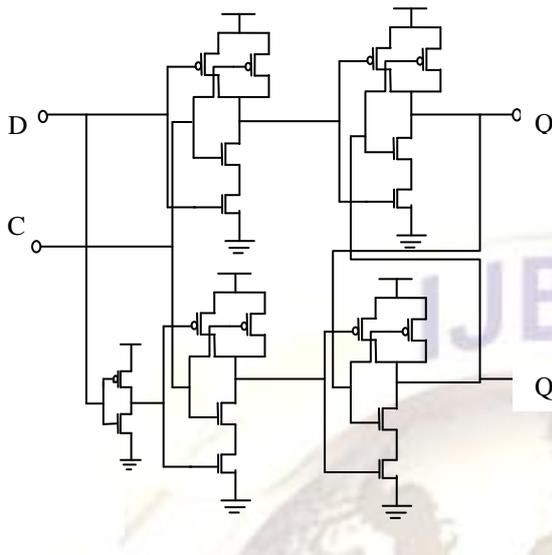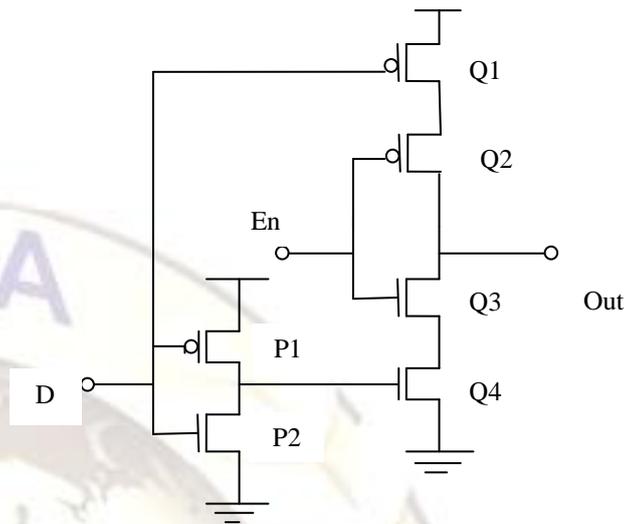

Figure 1: D Flip-Flop[2]

Figure 2 : Tri-state Buffer[2]

Table 1

Clock	D	O(next)
Rising edge	0	0
Rising edge	1	1
Non-rising	non	Q

Truth Table of D flip-flop

Table 2

Enable	Input	Output
1	0	0
1	1	1
0	0	Hi-Z
0	1	Hi-Z

Truth Table of Tri-state buffer

B. Tri-state buffer

Tri-state or 3-state logic allows an output port to assume a high impedance state in addition to the 0 and 1 logic levels, effectively removing the output from the circuit. This allows multiple circuits to share the same output line or lines (such as a bus).

The whole concept of the third state (Hi-Z) is to effectively remove the device's influence from the rest of the circuit. If more than one device is electrically connected, putting an output into the Hi-Z state is often used to prevent short circuits, or one device driving high (logical 1) against another device driving low (logical 0).

Basically Tri-state buffer design in two part, (P1,P2) works as a inverter and (Q2, Q3) uses as a enable circuit. When enable is high data will come at the outpu , it may be any logic 0 or 1 and if enable is low the output will be in high impedance state.

C. Elastic buffer design using D flip-flop

As mention above when we design elastic buffer using DFF then it consume more power also more propagation delay.If we design elastic buffer using tri-state buffer then it consume less power and propagation delay also it gives the benefits of third logic of tri-state which is high impedance state of it.
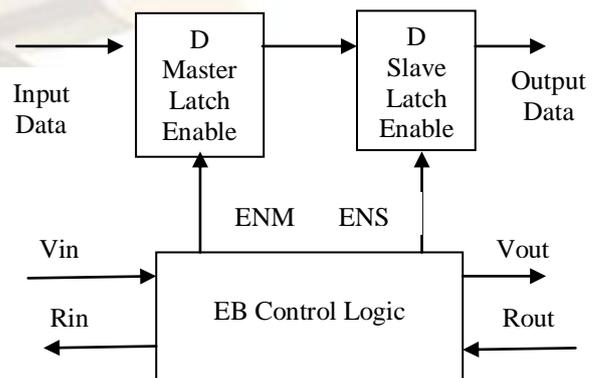

Figure 3 : Elastic Buffer using D flip-flop[1]

Elastic buffer using D flip-flop using master and slave latches. By adding control logic to drive the latch enable pins independently, each latch can be used as an independent storage location. Thus, the Flip-flop becomes an Elastic Buffer, a First-In-First-Out with two storage locations. This is illustrated in Figure. Elastic Buffer channels use many such EBs to form a distributed FIFO.

III. PROPOSED WORK

The whole concept of the third state (Hi-Z) is to effectively remove the device's influence from the rest of the circuit. If more than one device is electrically connected, putting an output into the Hi-Z state is often used to prevent short circuits, or one device driving high (logical 1) against another device driving low (logical 0).

When we use tri-state buffer in place of D flip-flop, the number of transistor reduced and remains only six in place of 18 transistors.

Since we have use two tri-state buffer as master-slave concept hence number of transistor needed is only 12 while master-slave using D flip-flop needed 36 transistor hence area cost is reduced.
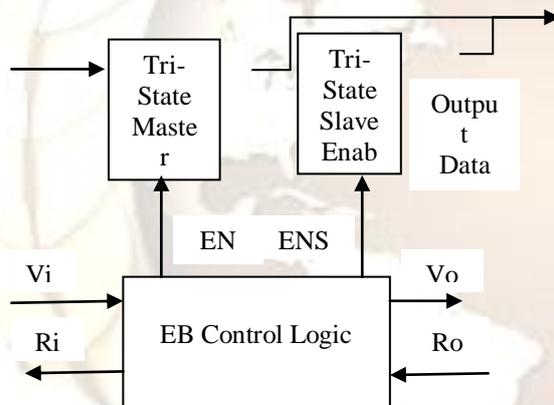

Figure 4 : Tri-State Elastic Buffer

Figure shows the D flip-flop is replaced by tri state buffer and whenever tri state buffer is enable it will copy the input to output and when it enable is low it goes in high state and do not copy the input into output like the D flip-flop.

Since tri-state buffer uses less transistor than D flip-flop hence result reduction in power and also reduces static and dynamic power both in some extent.

When we calculate delay in D flip-flop and tri-state buffer for the same reason it also get decrease.

IV. COMPARISION

Total power of elastic buffer design using D flip-flop is 40.90 µW and total power of Tri-state elastic buffer design is 20.987 µW. Hence reduction in total power of elastic buffer design using tri-state buffer is 48.68 %. Figure 7 shows the result of output waveform from which total power of elastic buffer

design using D flip-flop is calculated and figure 8 shows the output waveform of tri-state buffer from which total power is calculated.

1) Propagation delay of elastic buffer design using D flip-flop is 80 ps and propagation delay in tri-state elastic buffer design is 75.5 ps. Hence reduction in propagation delay is 5.62 %. figure 7 shows the calculator window which shows the propagation delay in D flip-flop and figure 8 shows the calculator window which shows the propagation delay in Tri-state buffer.

2) Area of elastic buffer design using D flip-flop is 1470.3 square meter and area in tri-state elastic buffer design 867.7 square meter. Hence reduction in area is 40.98 %. figure 5 shows the calculator window which shows the area in D flip-flop and figure 6 shows the calculator window which shows the area in Tri-state buffer.

3) When D flip-flop is not enable, there is no change in output but in tri-state when it is not enable output goes in High impedance state.

V. CONCLUSION

We propose a novel approach named tri-state elastic buffer design which reduces the total power, delay and area of elastic buffer. Total power of Tri-state elastic buffer is reduced 22.50% as compared to total power of elastic buffer design using D flip-flop. Propagation delay in tri-state elastic buffer is reduced 89.67% as compared to propagation delay of elastic buffer design using D flip-flop. Area in tri-state elastic buffer is reduced 89.67% as compared to area of elastic buffer design using D flip-flop and provide the advantage of high impedance of tri-state buffer.

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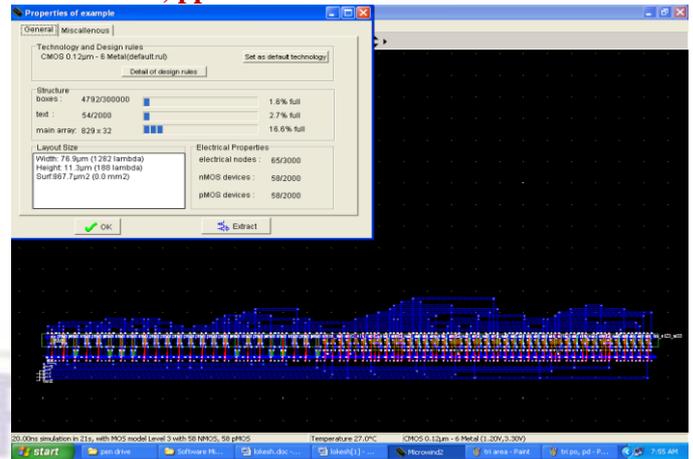
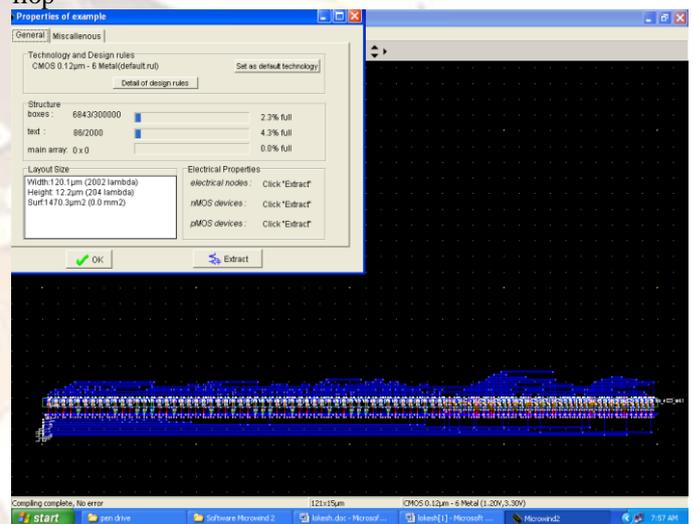Figure 5: Area in Elastic buffer design using D flip-flop

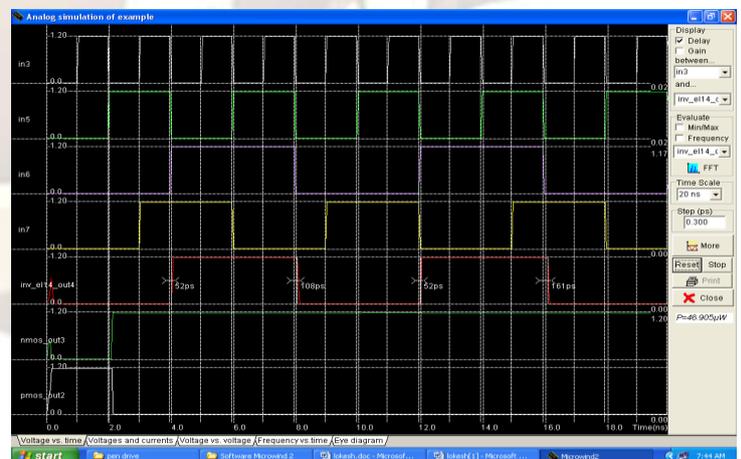Figure 6 : Area in tri-state elastic buffer design

Figure 7 : Output waveform of Elastic buffer design D f-f

Figure 8 : output waveform of tri-state elastic buffer design